

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
TAO CHENG	10/16/2015
WEN-SUNG HSU	10/16/2015
SHIH-CHIN LIN	10/16/2015
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	MEDIATEK INC.
<b>Street Address:</b>	NO. 1, DUSING RD. 1ST
<b>Internal Address:</b>	SCIENCE-BASED INDUSTRIAL PARK
<b>City:</b>	HSIN-CHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15420140
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(404)521-4286
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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<b>ATTORNEY DOCKET NUMBER:</b>	251311-1551
<b>NAME OF SUBMITTER:</b>	DANIEL R. MCCLURE
<b>SIGNATURE:</b>	/Daniel R. McClure/
<b>DATE SIGNED:</b>	01/31/2017
	This document serves as an Oath/Declaration (37 CFR 1.63).
<b>Total Attachments: 2</b>	

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ASSIGNMENT OF AND DECLARATION FOR APPLICATION FOR UNITED STATES LETTERS PATENT

WHEREAS Tao Cheng, Wen-Sung Hsu and Shih-Chin Lin

, hereinafter referred to collectively as the assignor and inventor, has invented a certain improvement relating to

COMPOSITE SOLDER BALL, SEMICONDUCTOR PACKAGE USING THE SAME, SEMICONDUCTOR DEVICE USING THE SAME AND MANUFACTURING METHOD THEREOF

said application being attached hereto;

said application having been filed in the United States Patent and Trademark Office on

..... as Application Serial No. .... and was amended on ..... (if applicable);

the specification of which was filed under the Patent Cooperation Treaty on .....

Serial No. .... the United States of America being designated

AND WHEREAS MEDIATEK Inc., hereinafter referred to as the assignee or applicant, is desirous of acquiring the entire right, title and interest in and to said application, including any and all divisions and continuations thereof, and in and to said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof;

NOW THIS WITNESSETH, that for good and valuable consideration paid by said assignee to said assignor, the receipt of which is hereby acknowledged, said assignor hereby assigns, sells and transfers to said assignee, and said assignee's successors and assigns, the full and exclusive right, title and interest in and to said application, including any and all divisions and continuations thereof, and in and to said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof; said assignee, and said assignee's successors and assigns, to have, hold, exercise and enjoy the said application, including any and all divisions and continuations thereof, and the said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof, with all the rights, powers, privileges and advantages in anywise arising from or appertaining thereto, for and during the term or terms of any and all such patents when granted, including any and all renewals, reissues and prolongations thereof, for the use and benefit of said assignee, and said assignee's successors and assigns, in as ample and beneficial a manner as the said assignor might or could have held and enjoyed the same, if this assignment had not been made.

AND said assignor hereby agrees to perform, upon the request of said assignee, or said assignee's successors or assigns, any and all acts relating to the obtaining or to the asserting of said patents, including any and all renewals, reissues and prolongations thereof.

AND said assignor authorizes and requests the Commissioner of Patents and Trademarks to issue Letters Patent on said application, and on any and all divisions and continuations thereof, to said assignee, and said assignee's successors and assigns, in accordance herewith.

As an above-named inventor, I hereby declare that the above-identified application was made or authorized to be made by me, and that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNOR (SOLE OR FIRST INVENTOR):

Signature: Tag Chang

Legal Name: Tag Chang

Date: 10/16/2015

ASSIGNOR (SECOND INVENTOR):

Signature: Wen-Sung Hsu

Legal Name: Wen-Sung Hsu

Date: 10/16/2015

ASSIGNOR (THIRD INVENTOR):

Signature: Shih-Chin Lin

Legal Name: Shih-Chin Lin

Date: 2015.10.16